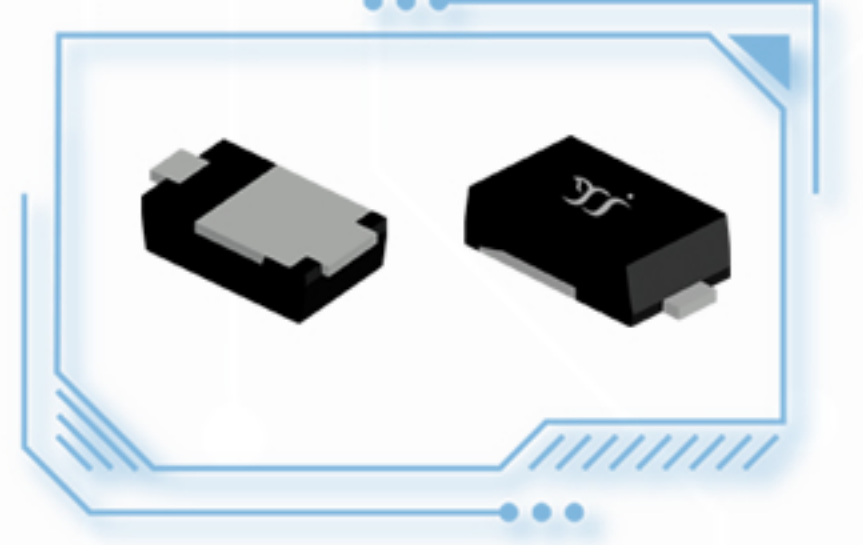


## SOD-123HE Diode

### Product Introduction

1. With ultra-thin package shape, it can be used in miniaturized and thin circuits;
2. The bottom side of the package has a heat sink, which has excellent heat dissipation performance;
3. There are many kinds of packaging chips, including GPP, DB, Schottky, FRED, TVS and other chips;
4. The product is made of environment-friendly materials and meets RoHS standards;
5. Products are widely used in secondary rectifier circuits, converters, freewheeling diodes, AC/DC power protection and so on.



### Product Features

1. Excellent heat dissipation performance: the back pad has large area, good heat dissipation performance and strong flow capacity, which can meet the requirements of high-temperature applications;
2. Thin package shape : the package shape is thinner than SOD-123FL package and meets the development trend of packaging thinness.



### Electrical Parameters

GPP Series				SKY Series			
P/N	Io(A)	IFSM (A)	VR (V)	P/N	Io(A)	IFSM (A)	VR (V)
G1AE-G1ME	1	30	50-1000	S14E-S120E	1	30	40-200
H1AE-H1ME	1	30	50-1000	S24E-S220E	2	50	40-200
F1AE-F1ME	1	30	50-1000	S34E-S320E	3	80	40-200
E1AE-E1KE	1	30	50-800	SL14E-SL120E	1	30	40-200
U1AE-U1JE	1	30	50-600	SL24E-SL220E	2	50	40-200
G2AE-G2ME	2	50	50-1000	SL34E-SL320E	3	60	40-200
H2AE-H2ME	2	50	50-1000				
F2AE-F2ME	2	50	50-1000				
E2AE-E2KE	2	50	50-800				
U2AE-U2JE	2	50	50-600				

Series		Peak power dissipation @10/1000μs waveform	Working Peak Reverse Voltage VRWM (V)	Maximum Reverse Surge Current IPP @10/1000μs waveform (A)	Package
SMFE Series	Uni/Bi	200W	5.0-400	0.31-21.74	SOD-123HE
SM4FE Series	Uni/Bi	400W	8.5-220	1.12-27.78	SOD-123HE

For more products, please refer to the official website

### Application

